

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Yuji NATORI, et al.

Serial No. : 09/679,747

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Group Art Unit: 2854

Date Filed : October 5, 2000

Examiner: R. Yan

HEAT-SENSITIVE STENCIL, PROCESS OF
FABRICATING SAME AND PRINTER USING SAME1185 Avenue of the Americas
New York, N.Y. 10036Assistant Commissioner for Patents
Washington, D.C. 20231AMENDMENT

Sir:

In response to the first Office Action dated March 28, 2002, please amend the above-identified application as follows:

In the Specification:

Page 2, paragraph 4, line 35.

In accomplishing the foregoing objects, there is provided in accordance with one aspect of the present invention a heat-sensitive stencil which includes a porous resin layer, and a resin film laminated on a porous resin layer, and a thin resin layer interposed between the porous resin layer and the resin film.

I hereby certify that this paper is being deposited this date with the U.S. Postal Service as first class mail addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Richard F. Jaworski
Reg. No. 33,515

Date

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